

Automotive IPD 2ch Low Side Switch

BM2LC120FJ-C

Features

- AEC-Q100 Qualified^(Note 1)
- Built-in Over Current Protection Function(OCP)
- Built-in Thermal Shutdown Function (TSD)
- Built-in Active Clamp Function
- Built-in Diagnostic Function
- Direct Control Enabled from CMOS Logic IC, etc.
- On Resistance $R_{DS(ON)} = 120\text{ m}\Omega$ (Typ)
- (when $V_{IN} = 5\text{ V}$, $I_{OUT} = 0.8\text{ A}$, $T_j = 25\text{ }^\circ\text{C}$)
- Monolithic Power Management IC with the Control Block (CMOS) and Power MOS FET Mounted on a Single Chip

(Note 1) Grade1

Key Specifications

On-state Resistance ($T_j = 25\text{ }^\circ\text{C}$, Typ)	120 m Ω
Over Current Detection Current ($T_j = 25\text{ }^\circ\text{C}$, Typ)	6 A
Output Clamp Voltage (Min)	42 V
Active Clamp Energy ($T_{j(START)} = 25\text{ }^\circ\text{C}$)	140 mJ

Package

SOP-J8

W (Typ) x D (Typ) x H (Max)

4.90mm x 6.00mm x 1.65mm



General Description

The BM2LC120FJ-C is an automotive 2ch low side switch IC, which has built-in OCP, TSD, active clamp function.

Also, diagnostic function can diagnose OCP, TSD, open load detection function (OLD).

Application

- Driving Resistive, Inductive and Capacitive Load

Block Diagram^(Note 1)

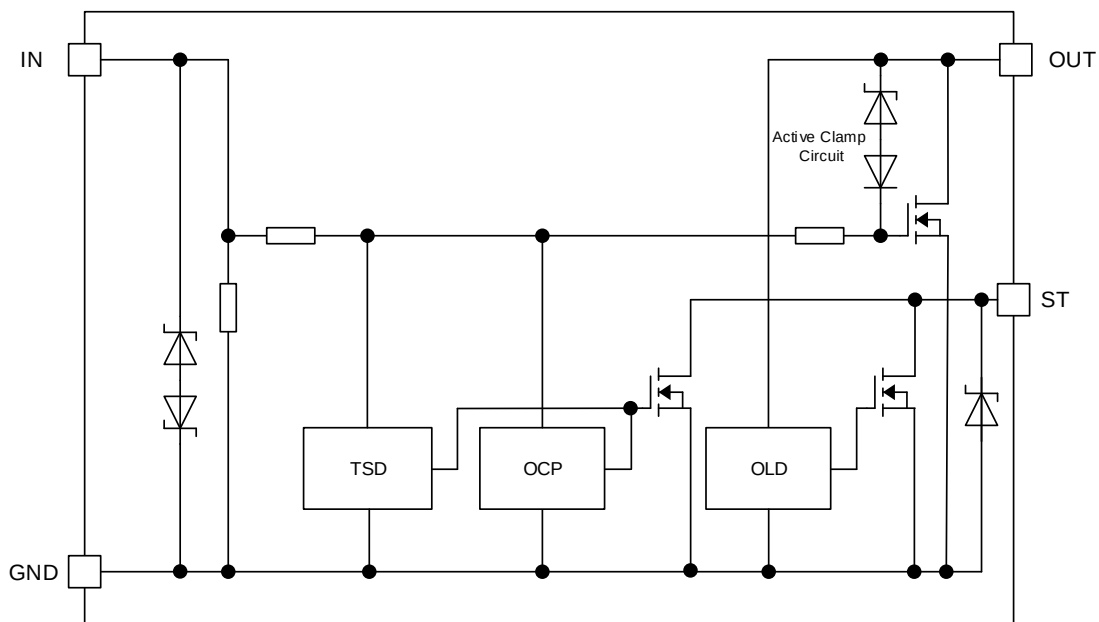


Figure 1. Block Diagram

(Note 1) There are two blocks in this product.

Contents

Features.....	1
General Description	1
Application	1
Key Specifications.....	1
Package.....	1
Block Diagram	1
Contents	2
Pin Configuration	3
Pin Description.....	3
Term.....	3
Absolute Maximum Ratings	4
Recommended Operating Conditions	4
Thermal Resistance	5
Electrical Characteristics.....	9
Typical Performance Curves.....	11
Measurement Circuit for Typical Performance Curves.....	18
I/O Pin Truth Table	20
Timing Chart	20
Function Description	22
Operational Notes.....	24
Ordering Information	25
Marking Diagram	25
Physical Dimension and Packing Information	26
Revision History.....	27

Pin Configuration

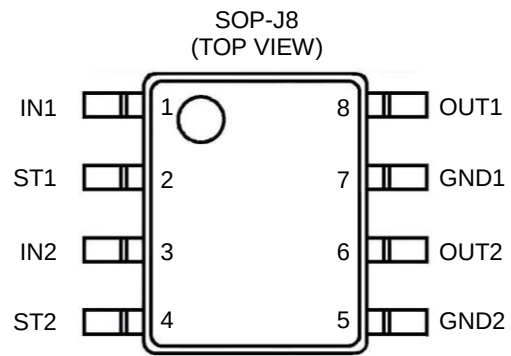


Figure 2. Pin Configuration

Pin Description

Pin No.	Pin Name ^(Note 1)	Function
1	IN1	Input pin 1, with internal pull-down resistor.
2	ST1	Self-diagnostic output pin 1.
3	IN2	Input pin 2, with internal pull-down resistor.
4	ST2	Self-diagnostic output pin 2.
5	GND2	GND pin 2.
6	OUT2	Output pin 2, when output pin shorted to battery and output current exceeding the over current detection value, output current will be limited to protect IC.
7	GND1	GND pin 1.
8	OUT1	Output pin 1. When output pin shorted to battery and output current exceeding the over current detection value, output current will be limited to protect IC.

(Note 1) The number in Pin Name is the channel number.

Term

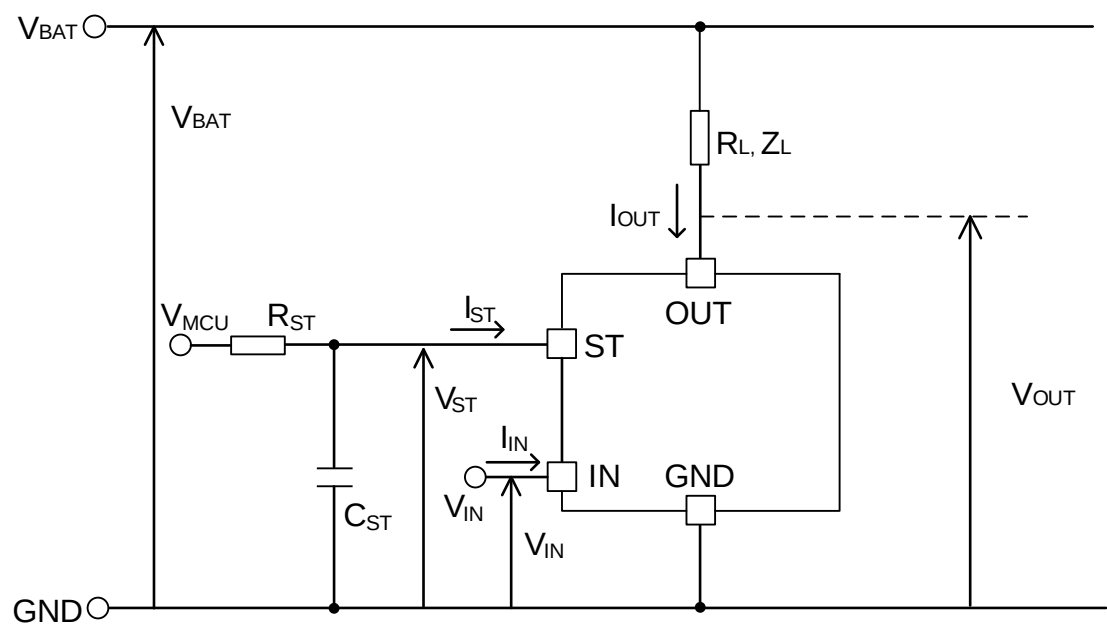


Figure 3. Term

Absolute Maximum Ratings(Tj = 25°C)

Parameter	Symbol	Ratings	Unit
Output Voltage	V _{OUT}	-0.3 to +42	V
Input Voltage	V _{IN}	-0.3 to +7	V
Output Current	I _{OUT(OCF)}	3.0 (inside limited) ^(Note 1)	A
Diagnostic Output Voltage	V _{ST}	-0.3 to +7	V
Diagnostic Output Current	I _{ST}	10	mA
Active Clamp Energy (Single Pulse) T _{J(START)} = 25 °C ^(Note 2)	E _{AS(25 °C)}	140	mJ
Active Clamp Energy (Single Pulse) T _{J(START)} = 150 °C ^{(Note 2) (Note 3)}	E _{AS(150 °C)}	50	
Operating Temperature Range	T _J	-40 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C
Maximum Junction Temperature	T _{jmax}	150	°C

Caution 1: Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins and the internal circuitry. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.

Caution 2: Should by any chance the maximum junction temperature rating be exceeded the rise in temperature of the chip may result in deterioration of the properties of the chip. In case of exceeding this absolute maximum rating, design a PCB boards with thermal resistance taken into consideration by increasing board size and copper area so as not to exceed the maximum junction temperature rating.

(Note 1) Internally limited by over current protection function.

(Note 2) Active clamp energy (Single Pulse), at the condition I_{OUT(START)} = 1.9 A, V_{BAT} = 16 V.

$$E_{AS} = \frac{1}{2} L I_{OUT(START)}^2 \times \left(1 - \frac{V_{BAT}}{V_{BAT} - V_{OUT(CL)}} \right)$$

(Note 3) Not 100 % tested.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Input Voltage	V _{IN}	3.0	5.0	5.5	V
Operating Temperature	T _J	-40	+25	+150	°C

Thermal Resistance^(Note 1)

Parameter	Symbol	Typ	Unit	Condition
SOP-J8 (1ch ON)				
Between Junction and Surroundings Temperature Thermal Resistance	θ_{JA}	167.9	°C/W	1s ^(Note 2)
		105.8	°C/W	2s ^(Note 3)
		85.6	°C/W	2s2p ^(Note 4)

Parameter	Symbol	Typ	Unit	Condition
SOP-J8 (All ch ON)				
Between Junction and Surroundings Temperature Thermal Resistance	θ_{JA}	141.5	°C/W	1s ^(Note 2)
		84.1	°C/W	2s ^(Note 3)
		67.1	°C/W	2s2p ^(Note 4)

(Note 1) The thermal impedance is based on JESD51-2A (Still-Air) standard. It is used the chip of BM2LC120FJ-C

(Note 2) JESD51-3 standard FR4 114.3 mm x 76.2 mm x 1.57 mm 1-layer (1s)

(Top copper foil: ROHM recommended Footprint + wiring to measure, 2 oz. copper.)

(Note 3) JESD51-5 standard FR4 114.3 mm x 76.2 mm x 1.60 mm 2-layers (2s)

(Top copper foil: ROHM recommended Footprint + wiring to measure/

Copper foil area on the reverse side of PCB: 74.2 mm x 74.2 mm,

copper (top & reverse side) 2 oz.)

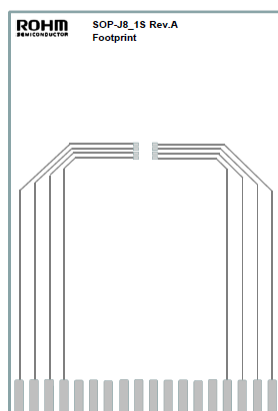
(Note 4) JESD51-5/-7 standard FR4 114.3 mm x 76.2 mm x 1.60 mm 4-layers (2s2p)

(Top copper foil: ROHM recommended Footprint + wiring to measure/

2 inner layers and copper foil area on the reverse side of PCB: 74.2 mm x 74.2 mm,

copper (top & reverse side/inner layers) 2 oz./1 oz.)

■ PCB Layout 1 layer (1s)



Footprint

Figure 4. PCB Layout 1 layer (1s)

Dimension	Value
Board Finish Thickness	1.57 mm ± 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top Layer)	0.070 mm (Cu:2 oz)

Thermal Resistance – continued

- PCB Layout 2 layers (2s)

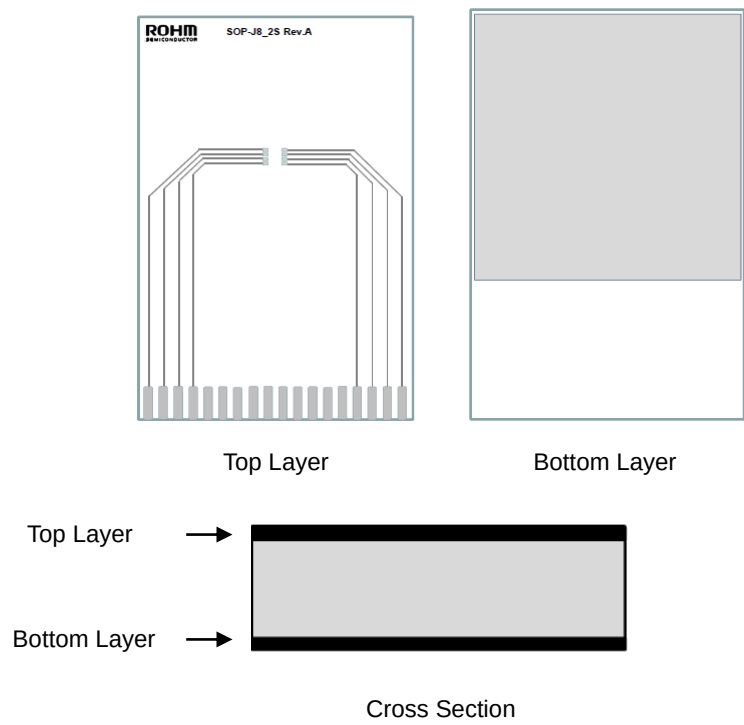


Figure 5. PCB Layout 2 layers (2s)

Dimension	Value
Board Finish Thickness	1.60 mm ± 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top/Bottom Layers)	0.070 mm (Cu + Plating)

Thermal Resistance – continued

- PCB Layout 4 layers (2s2p)

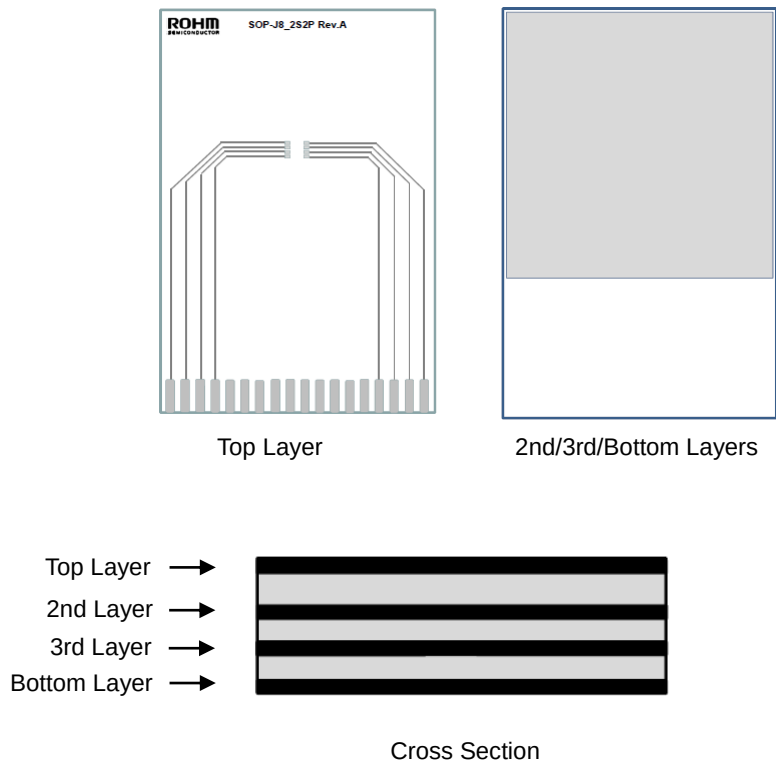


Figure 6. PCB Layout 4 layers (2s2p)

Dimension	Value
Board Finish Thickness	1.60 mm ± 10 %
Board Dimension	76.2 mm x 114.3 mm
Board Material	FR4
Copper Thickness (Top/Bottom Layers)	0.070 mm (Cu + Plating)
Copper Thickness (Inner Layers)	0.035 mm

Thermal Resistance – continued

- Transient Thermal Resistance (Single Pulse) 1ch ON

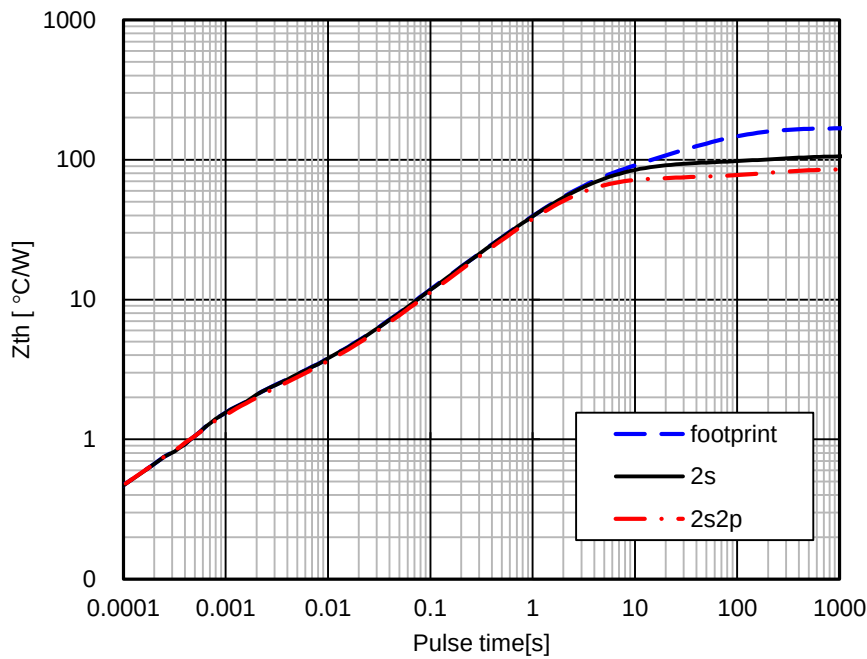


Figure 7. Transient Thermal Resistance

- Transient Thermal Resistance (Single Pulse) All ch ON

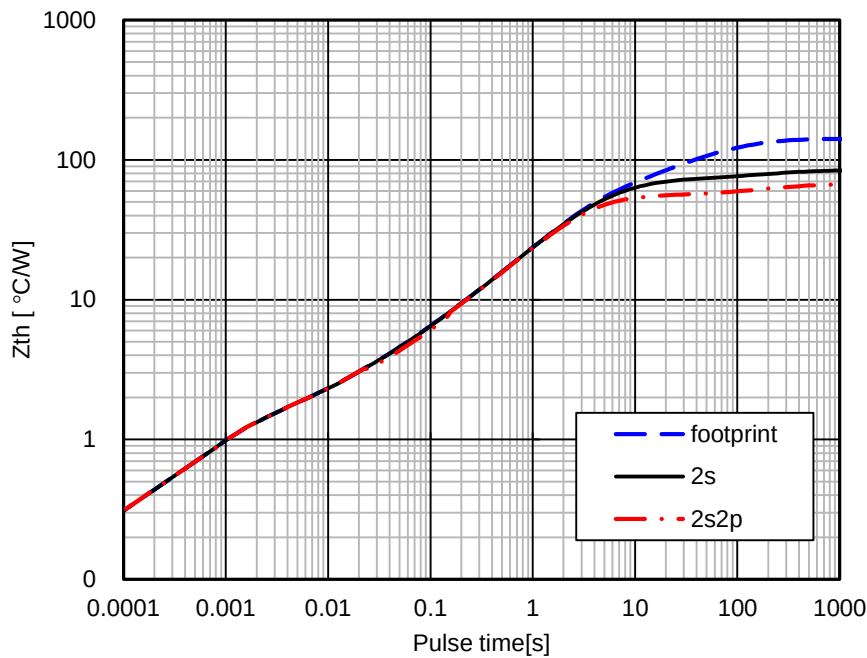


Figure 8. Transient Thermal Resistance

Electrical Characteristics (Unless otherwise specified, $-40\text{ }^{\circ}\text{C} \leq T_j \leq +150\text{ }^{\circ}\text{C}$)

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Output Clamp Voltage	$V_{OUT(CL)}$	42	48	54	V	$V_{IN} = 0\text{ V}, I_{OUT} = 1\text{ mA}$
On-state Resistance ($V_{IN} = 5\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$)	$R_{DS(ON)}$	-	120	160	m Ω	$V_{IN} = 5\text{ V}, I_{OUT} = 0.8\text{ A}, T_j = 25\text{ }^{\circ}\text{C}$
On-state Resistance ($V_{IN} = 5\text{ V}, T_j = 150\text{ }^{\circ}\text{C}$)	$R_{DS(ON)}$	-	230	300	m Ω	$V_{IN} = 5\text{ V}, I_{OUT} = 0.8\text{ A}, T_j = 150\text{ }^{\circ}\text{C}$
On-state Resistance ($V_{IN} = 3\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$)	$R_{DS(ON)}$	-	160	230	m Ω	$V_{IN} = 3\text{ V}, I_{OUT} = 0.8\text{ A}, T_j = 25\text{ }^{\circ}\text{C}$
On-state Resistance ($V_{IN} = 3\text{ V}, T_j = 150\text{ }^{\circ}\text{C}$)	$R_{DS(ON)}$	-	290	420	m Ω	$V_{IN} = 3\text{ V}, I_{OUT} = 0.8\text{ A}, T_j = 150\text{ }^{\circ}\text{C}$
Leak Current ($T_j = 25\text{ }^{\circ}\text{C}$)	$I_{OUT(L)}$	40	60	80	μA	$V_{IN} = 0\text{ V}, V_{OUT} = 18\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Leak Current ($T_j = 150\text{ }^{\circ}\text{C}$)	$I_{OUT(L)}$	50	85	200	μA	$V_{IN} = 0\text{ V}, V_{OUT} = 18\text{ V}, T_j = 150\text{ }^{\circ}\text{C}$
Turn-ON TIME	t_{ON}	-	-	60	μs	$V_{IN} = 0\text{ V to } 5\text{ V}, R_L = 15\text{ }\Omega, V_{BAT} = 12\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Turn-OFF TIME	t_{OFF}	-	-	60	μs	$V_{IN} = 5\text{ V to } 0\text{ V}, R_L = 15\text{ }\Omega, V_{BAT} = 12\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Slew Rate On	SR_{ON}	-	1.3	2.5	V/ μs	$V_{IN} = 0\text{ V to } 5\text{ V}, R_L = 15\text{ }\Omega, V_{BAT} = 12\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Slew Rate Off	SR_{OFF}	-	1.5	2.7	V/ μs	$V_{IN} = 5\text{ V to } 0\text{ V}, R_L = 15\text{ }\Omega, V_{BAT} = 12\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Input Threshold Voltage	$V_{IN(TH)}$	1.5	-	2.7	V	$R_L = 15\text{ }\Omega, V_{BAT} = 12\text{ V}$
High-level Input Current1 (in Normal Operation)	$I_{IN(H1)}$	-	125	250	μA	$V_{IN} = 5\text{ V}$
High-level Input Current2 (in Abnormal Operation) ^(Note 1)	$I_{IN(H2)}$	-	-	500	μA	$V_{IN} = 5\text{ V}$
Low-level Input Current	$I_{IN(L)}$	-10	0	+10	μA	$V_{IN} = 0\text{ V}$
Over Current Detection Current	$I_{OUT(OCF)}$	3	6	9	A	$V_{IN} = 5\text{ V}, V_{BAT} = 12\text{ V}, T_j = 25\text{ }^{\circ}\text{C}$
Thermal Shutdown Operated Temperature ^(Note 2)	T_{JO}	150	175	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$
Thermal Shutdown Released Temperature ^(Note 2)	T_{JR}	135	-	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$
Thermal Shutdown Hysteresis ^(Note 2)	$T_{J\Delta HYS}$	-	15	-	$^{\circ}\text{C}$	$V_{IN} = 5\text{ V}$

(Note 1) When thermal shutdown function or over current protection function is ON.

(Note 2) Not 100 % tested.

Electrical Characteristics (Unless otherwise specified, $-40\text{ }^{\circ}\text{C} \leq T_j \leq +150\text{ }^{\circ}\text{C}$) – continued

Parameter	Symbol	Limit			Unit	Conditions
		Min	Typ	Max		
Open Load Detection Voltage	V_{OPEN}	1.5	-	4.5	V	$V_{\text{IN}} = 0\text{ V}$
ST Output On Voltage1	$V_{\text{ST(ON1)}}$	-	0.2	0.5	V	$V_{\text{IN}} = 5\text{ V}$, $I_{\text{ST}} = 1\text{ mA}$
ST Output On Voltage2	$V_{\text{ST(ON2)}}$	-	0.2	0.5	V	$V_{\text{IN}} = 0\text{ V}$, $V_{\text{OUT}} = 4.5\text{ V}$, $I_{\text{ST}} = 0.5\text{ mA}$
ST Output Leak Current1	$I_{\text{ST(L1)}}$	-	-	20	μA	$V_{\text{IN}} = 5\text{ V}$, $V_{\text{ST}} = 5\text{ V}$
ST Output Leak Current2	$I_{\text{ST(L2)}}$	-	-	20	μA	$V_{\text{IN}} = 0\text{ V}$, $V_{\text{OUT}} = 1.5\text{ V}$, $V_{\text{ST}} = 5\text{ V}$
ST Output Delay Time Detect	t_{STDET}	-	1	30	μs	$V_{\text{IN}} = 0\text{ V}$, $V_{\text{OUT}} = 5\text{ V to }1\text{ V}$, $V_{\text{MCU}} = 5\text{ V}$, $R_{\text{ST}} = 10\text{ k}\Omega$, $C_{\text{ST}} = 10\text{ pF}$
ST Output Delay Time Release	t_{STREL}	-	1	30	μs	$V_{\text{IN}} = 0\text{ V}$, $V_{\text{OUT}} = 1\text{ V to }5\text{ V}$, $V_{\text{MCU}} = 5\text{ V}$, $R_{\text{ST}} = 10\text{ k}\Omega$, $C_{\text{ST}} = 10\text{ pF}$

Typical Performance Curves(Unless otherwise specified, $T_j = 25\text{ }^{\circ}\text{C}$, $V_{IN} = 5.0\text{ V}$)

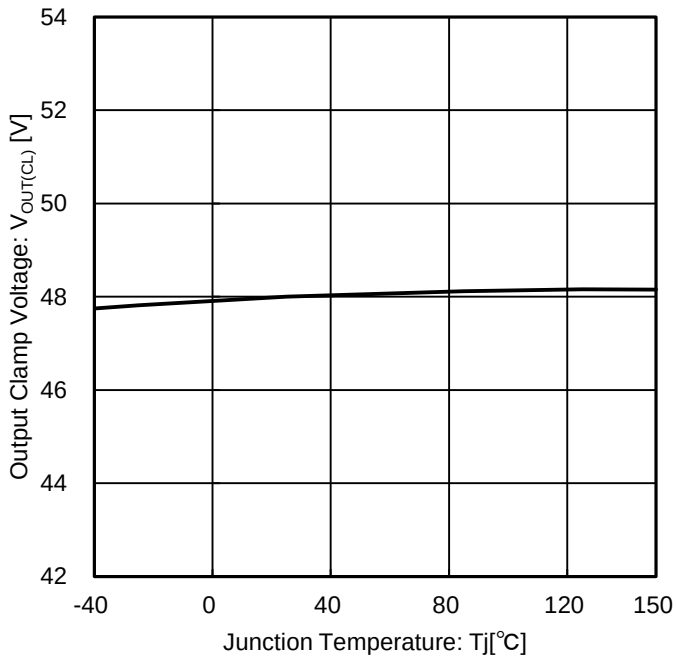


Figure 9. Output Clamp Voltage vs Junction Temperature

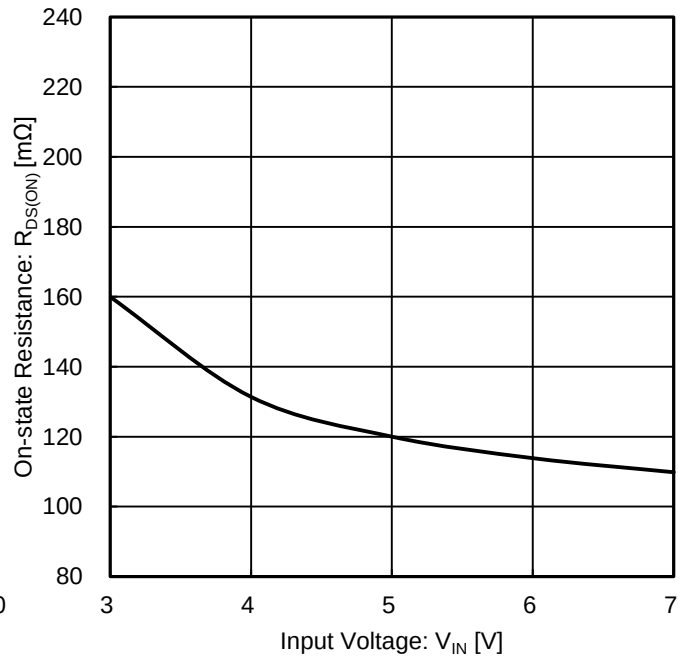


Figure 10. On-state Resistance vs Input Voltage

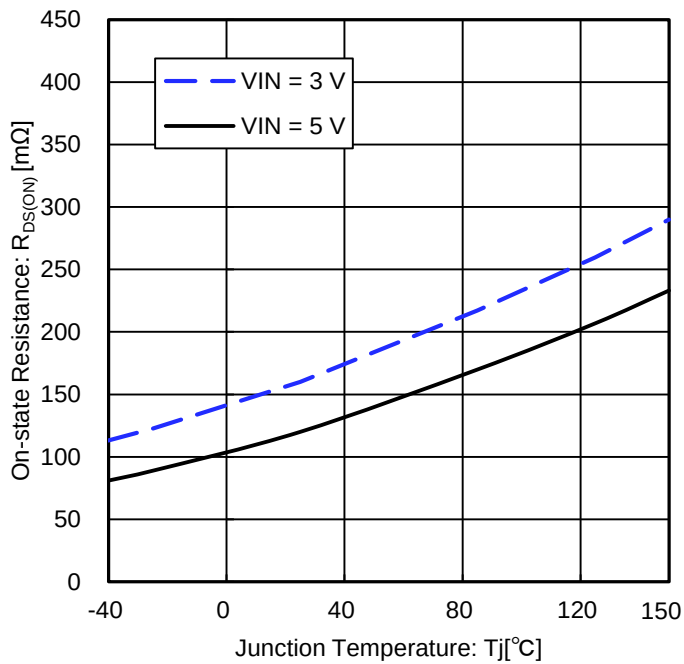


Figure 11. On-state Resistance vs Junction Temperature

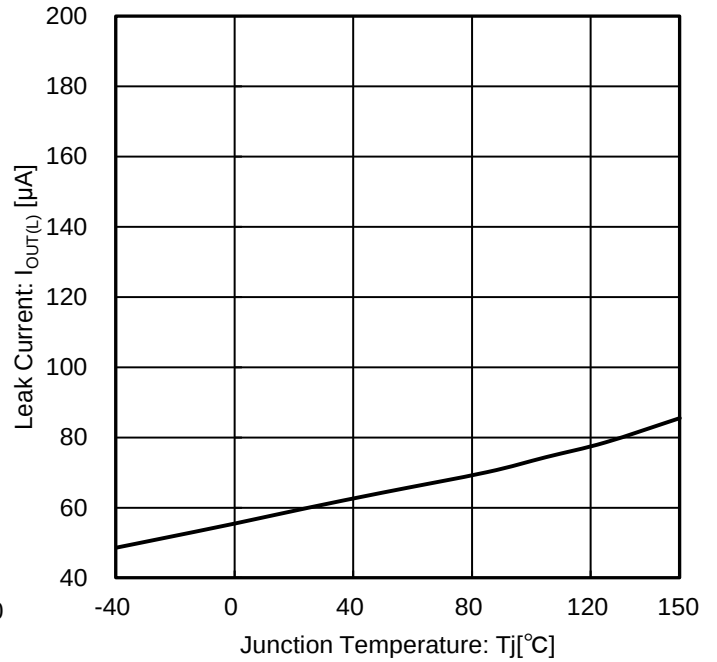


Figure 12. Leak Current vs Junction Temperature

Typical Performance Curves (Unless otherwise specified, Tj = 25 °C, VIN = 5.0 V) – continued

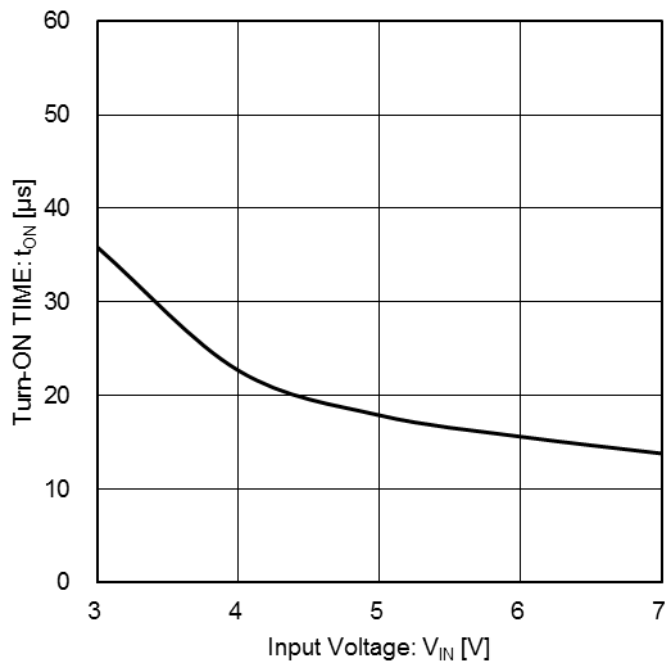


Figure 13. Turn-ON TIME vs Input Voltage

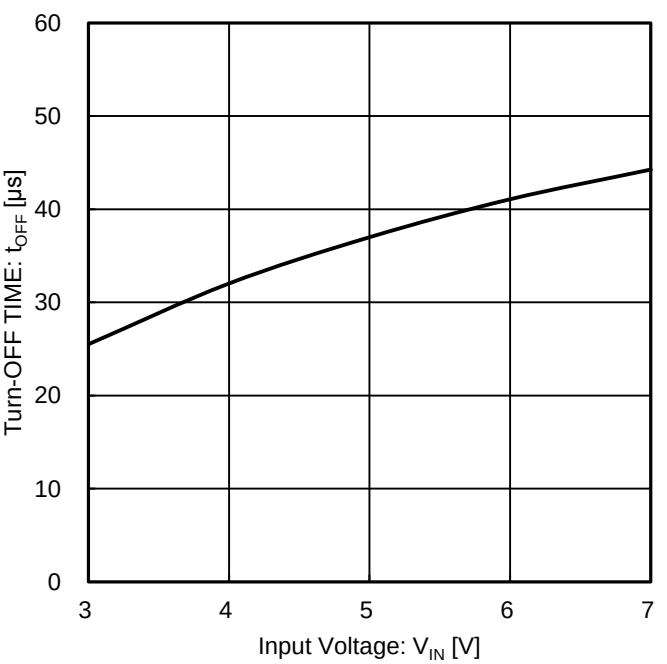


Figure 14. Turn-OFF TIME vs Input Voltage

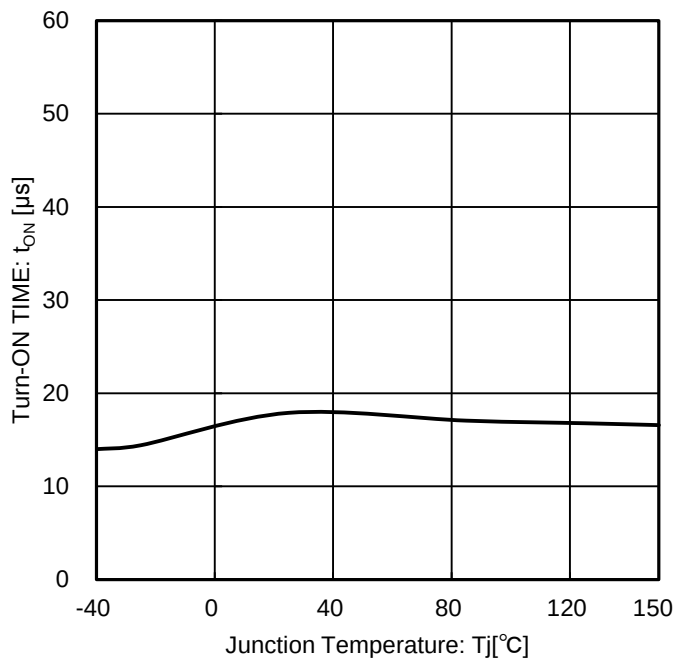


Figure 15. Turn-ON TIME vs Junction Temperature

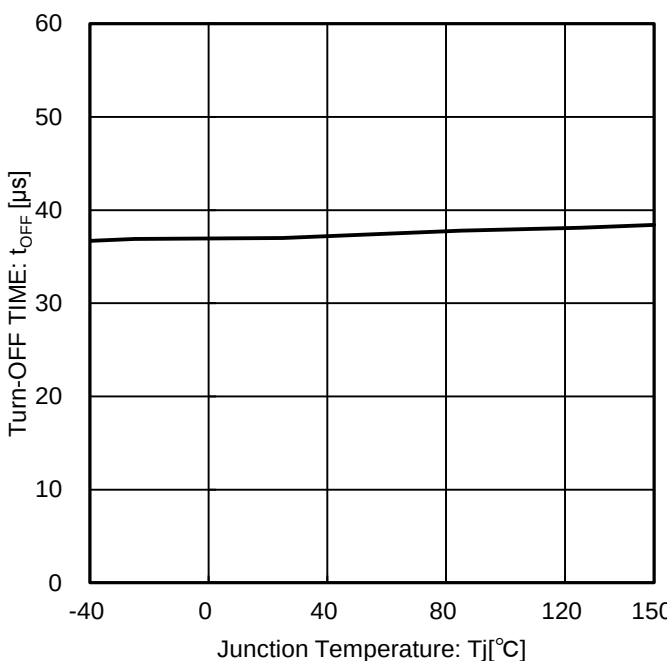


Figure 16. Turn-OFF TIME vs Junction Temperature

Typical Performance Curves (Unless otherwise specified, Tj = 25 °C, VIN = 5.0 V) – continued

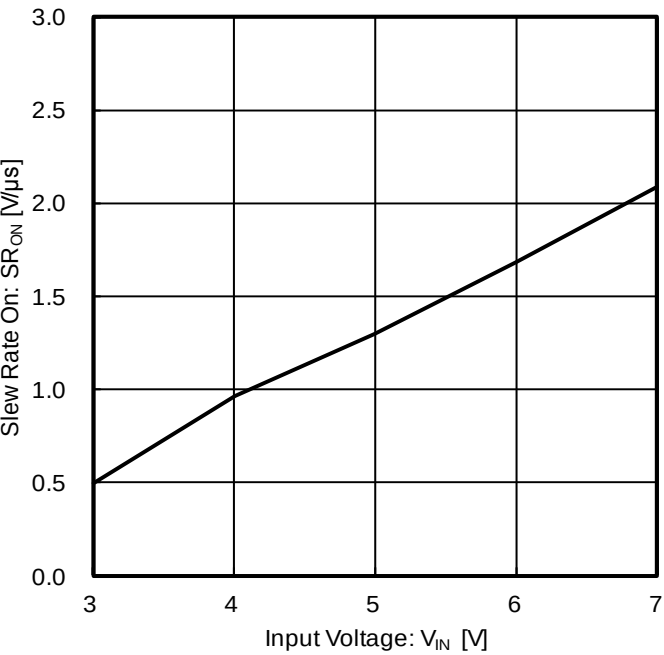


Figure 17. Slew Rate On vs Input Voltage

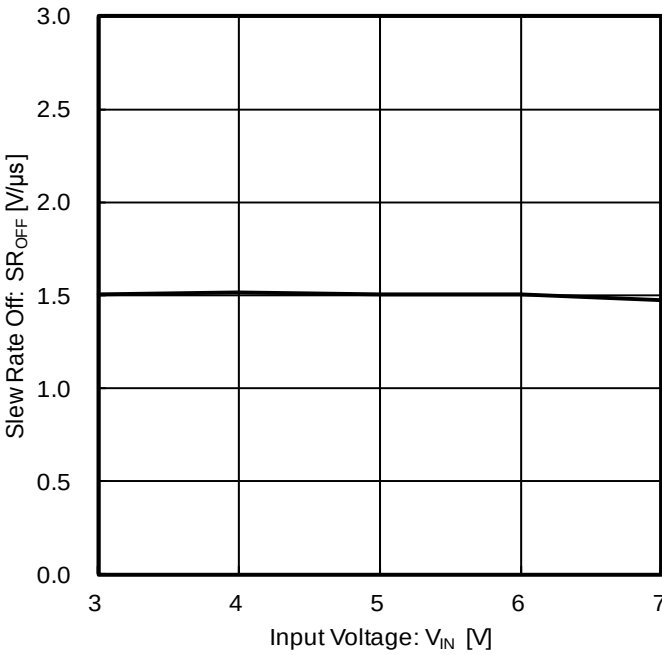


Figure 18. Slew Rate Off vs Input Voltage

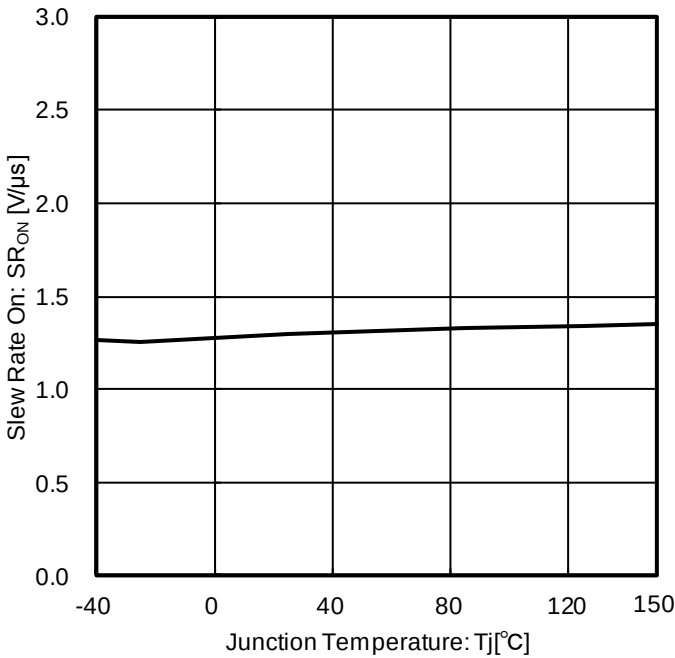


Figure 19. Slew Rate On vs Junction Temperature

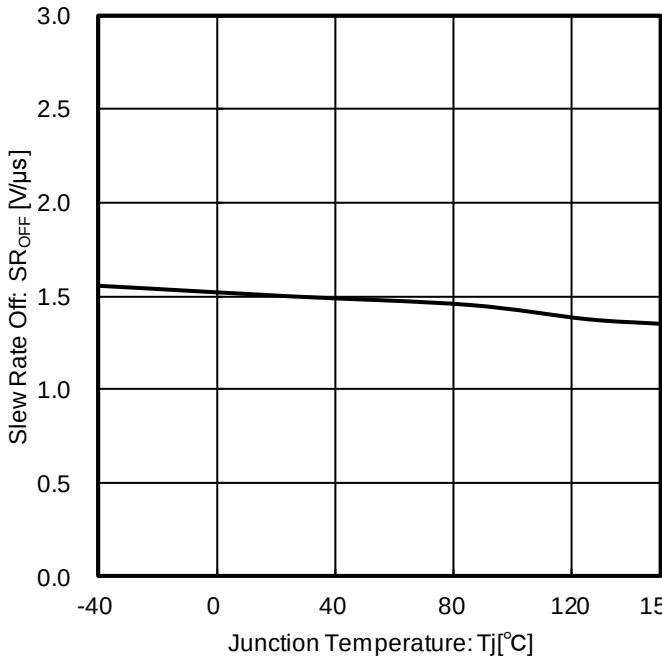


Figure 20. Slew Rate off vs Junction Temperature

Typical Performance Curves (Unless otherwise specified, $T_j = 25\text{ }^{\circ}\text{C}$, $V_{IN} = 5.0\text{ V}$) – continued

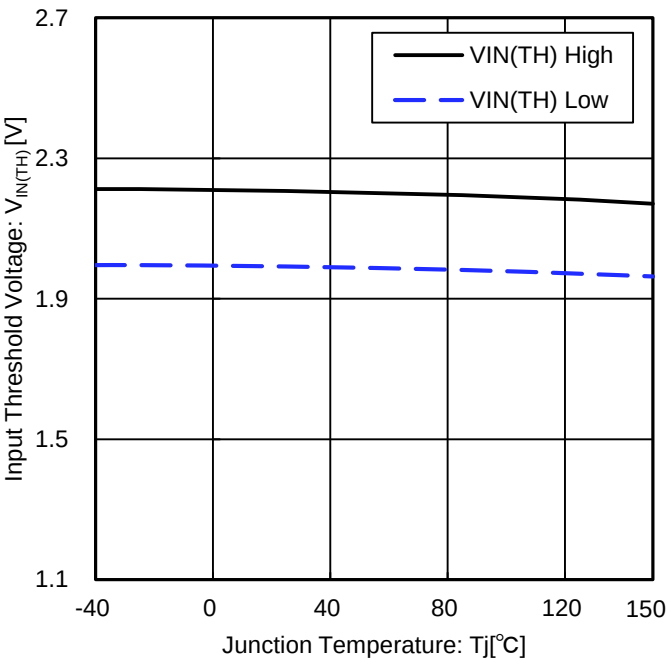


Figure 21. Input Threshold Voltage vs Junction Temperature

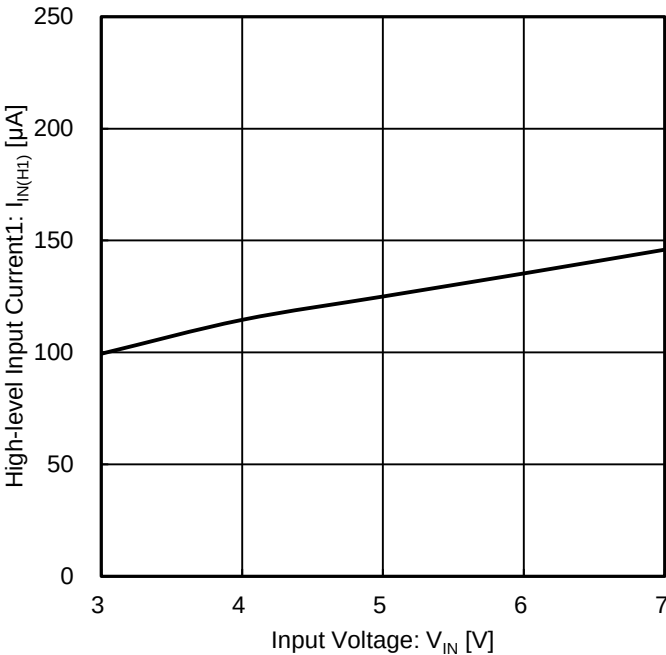


Figure 22. High-level Input Current1 (In Normal Operation) vs Input Voltage

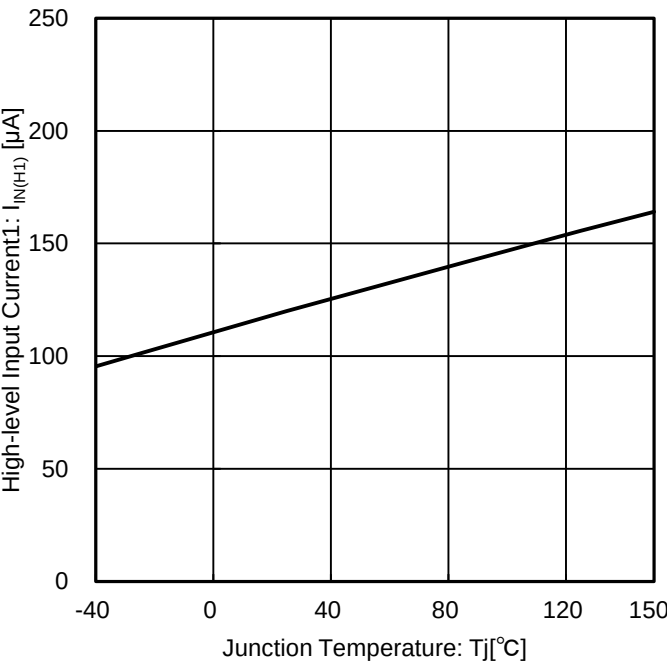


Figure 23. High-level Input Current1 (in Normal Operation) vs Junction Temperature

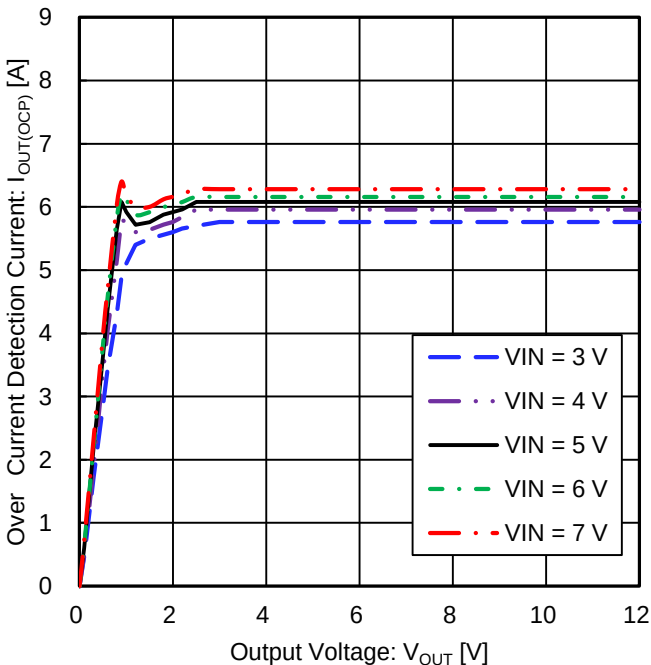


Figure 24. Over Current Detection Current vs Output Voltage

Typical Performance Curves (Unless otherwise specified, $T_j = 25\text{ }^{\circ}\text{C}$, $V_{IN} = 5.0\text{ V}$) – continued

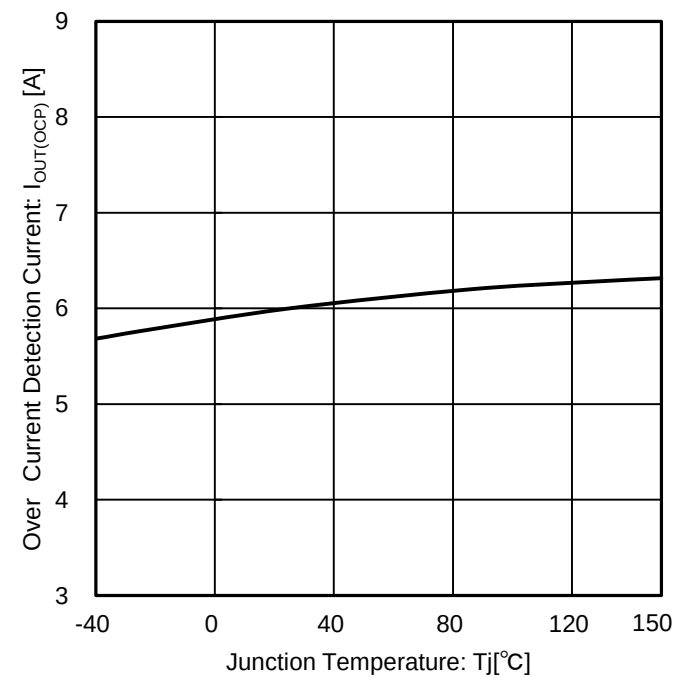


Figure 25. Over Current Detection Current vs Junction Temperature

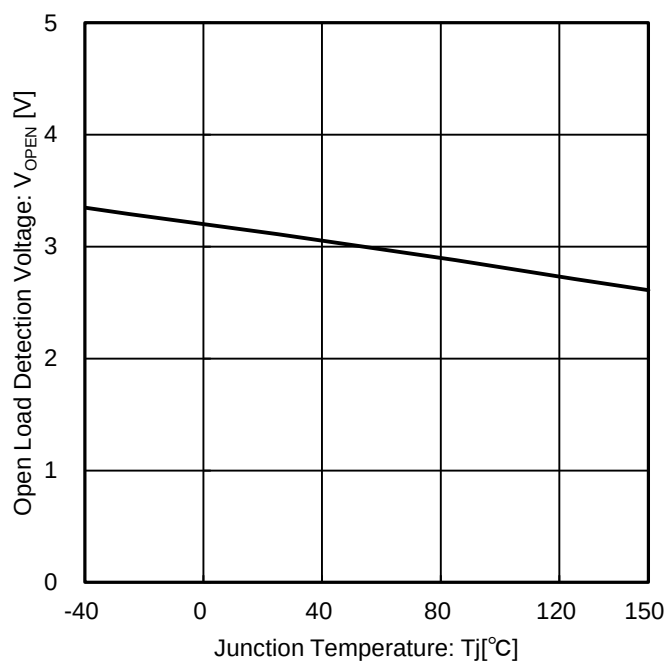


Figure 26. Open Load Detection Voltage vs Junction Temperature

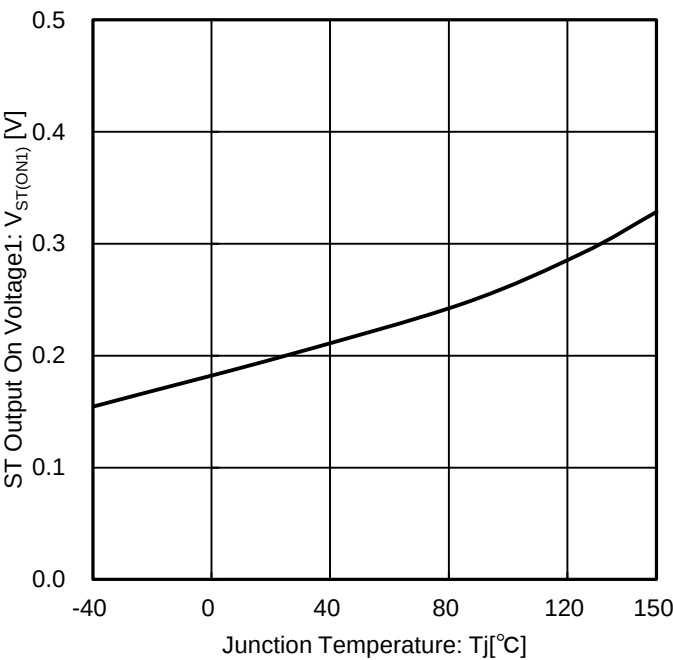


Figure 27. ST Output On Voltage1 vs Junction Temperature

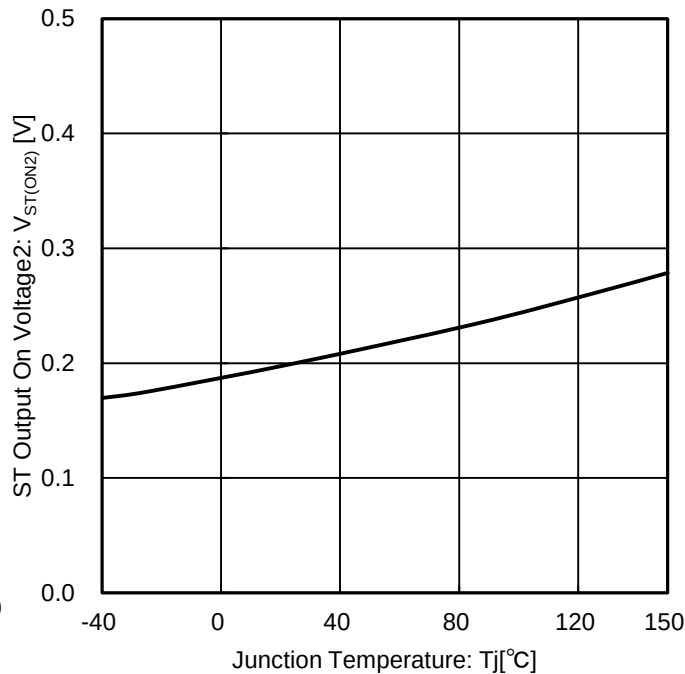


Figure 28. ST Output On Voltage2 vs Junction Temperature

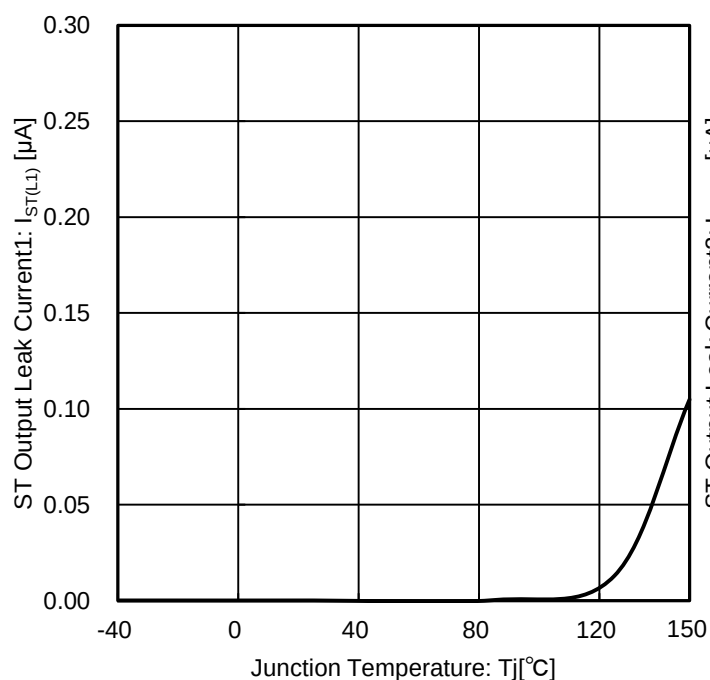
Typical Performance Curves (Unless otherwise specified, $T_j = 25\text{ }^{\circ}\text{C}$, $V_{IN} = 5.0\text{ V}$) – continued

Figure 29. ST Output Leak Current1 vs Junction Temperature

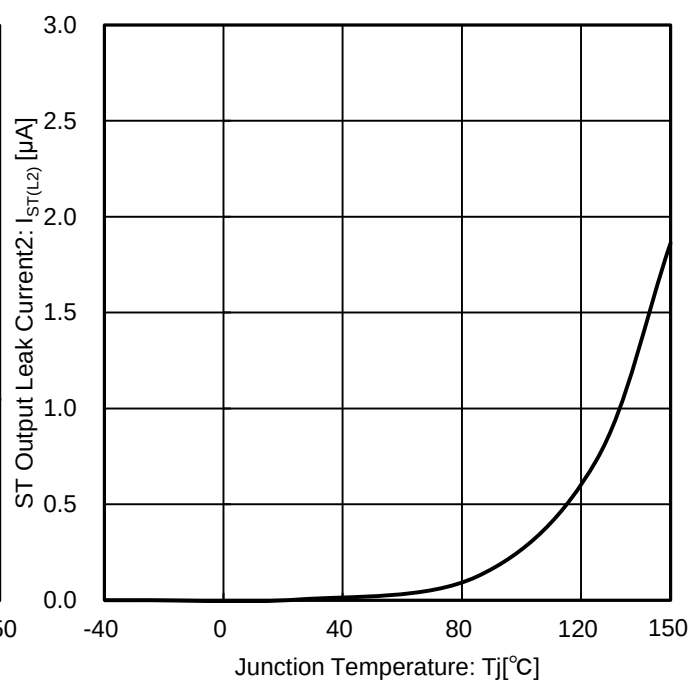


Figure 30. ST Output Leak Current2 vs Junction Temperature

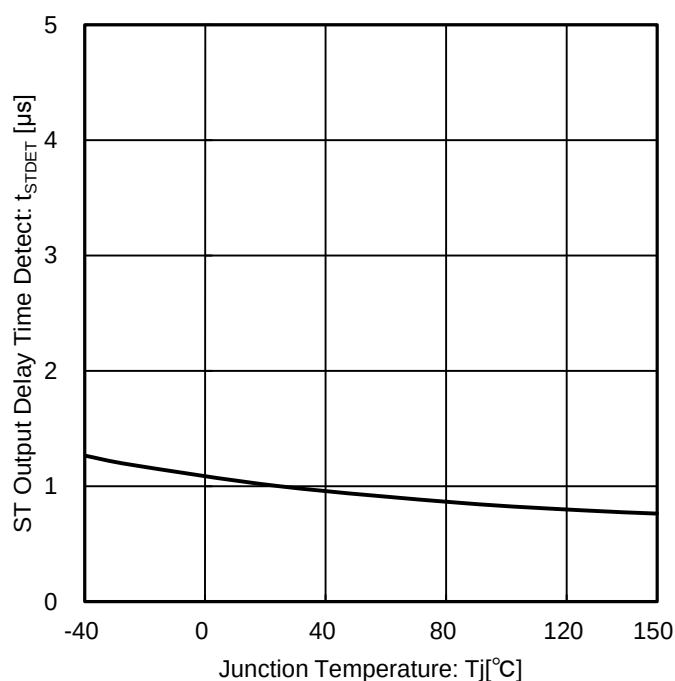


Figure 31. ST Output Delay Time Detect vs Junction Temperature

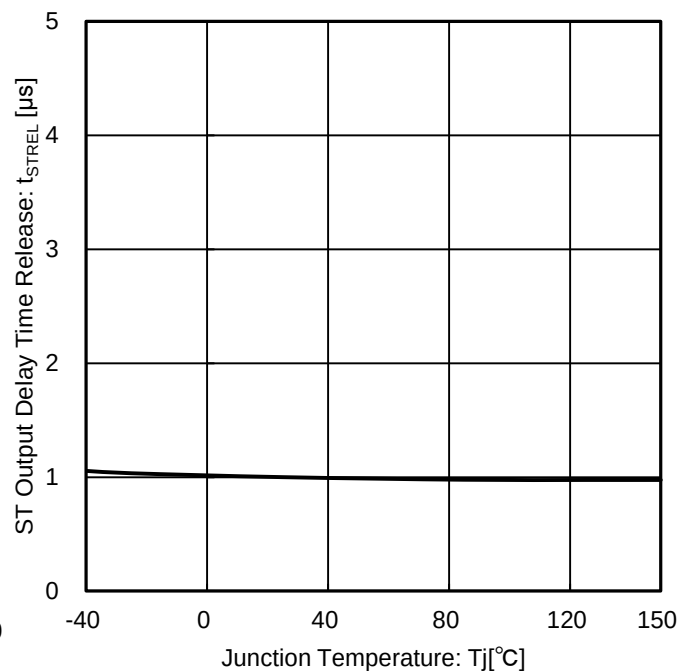


Figure 32. ST Output Delay Time Release vs Junction Temperature

Typical Performance Curves (Unless otherwise specified, Tj = 25 °C, VIN = 5.0 V) – continued

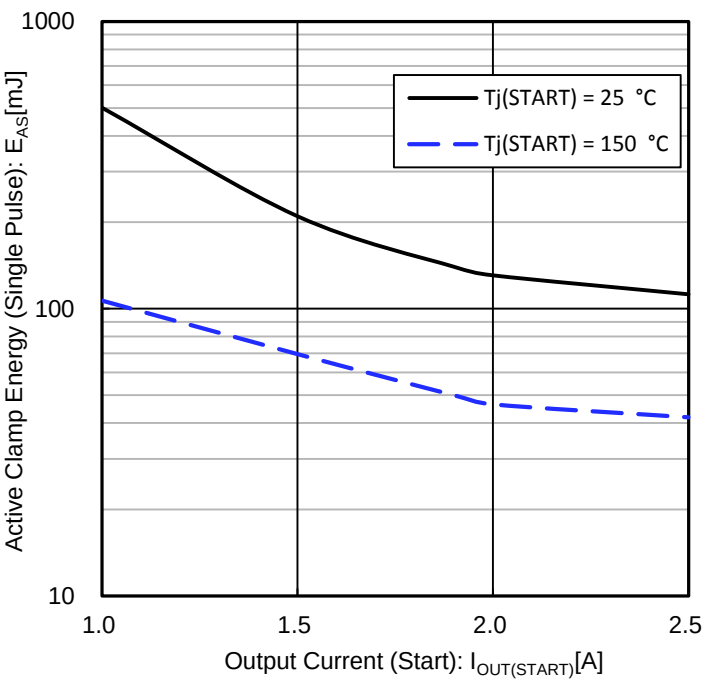
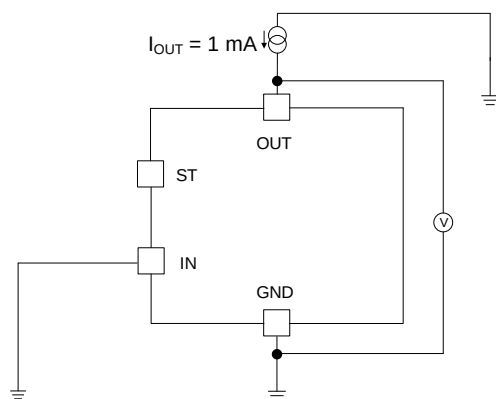
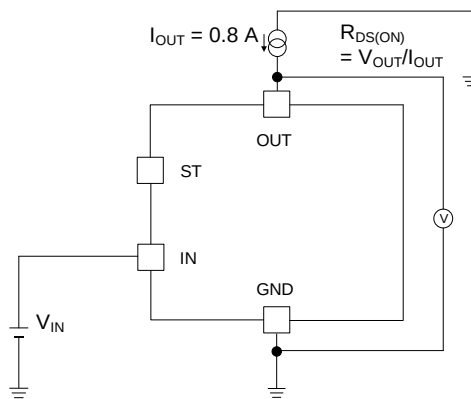


Figure 33. Active Clamp Energy (Single Pulse) vs Output Current (Start)

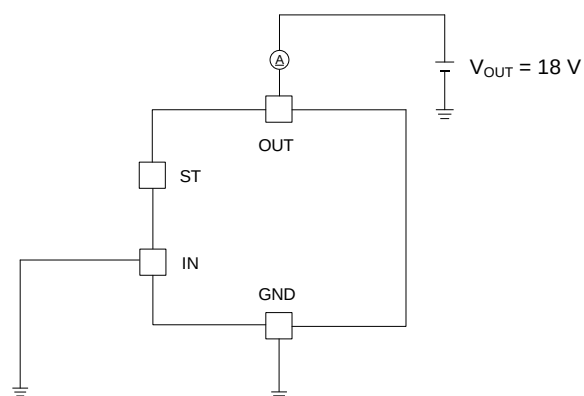
Measurement Circuit for Typical Performance Curves



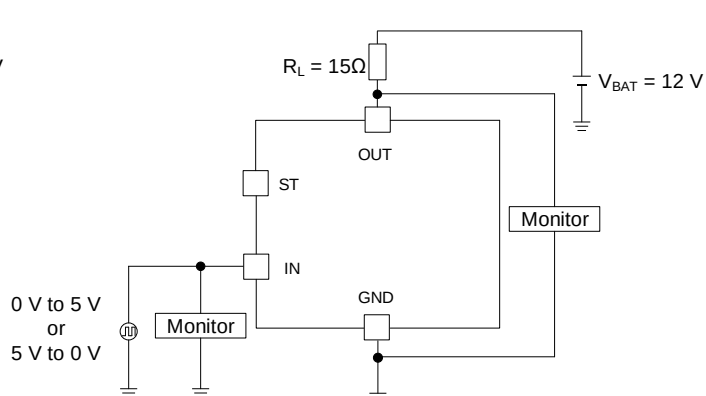
Measurement Circuit for Figure 9



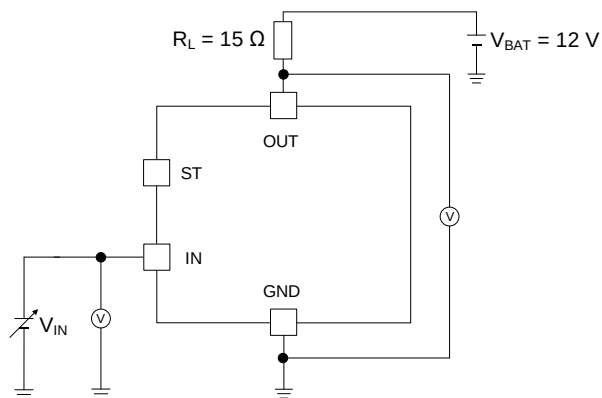
Measurement Circuit for Figure 10, 11



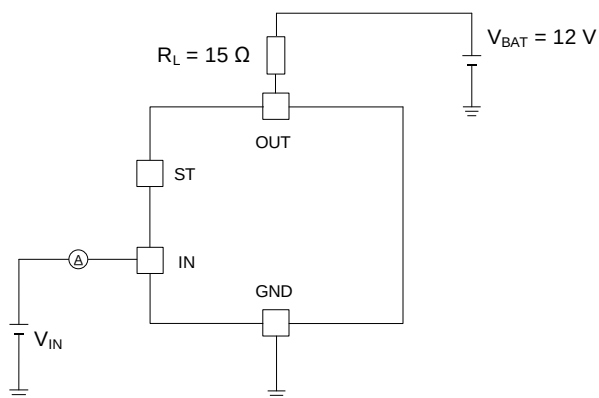
Measurement Circuit for Figure 12



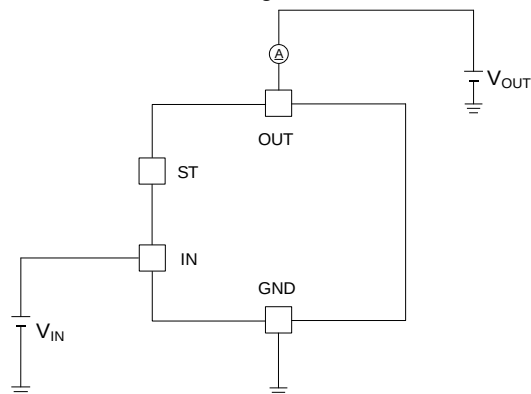
Measurement Circuit for Figure 13, 14, 15, 16, 17, 18, 19, 20



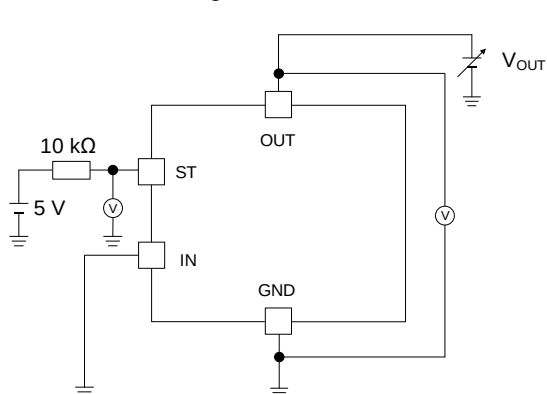
Measurement Circuit for Figure 21



Measurement Circuit for Figure 22, 23

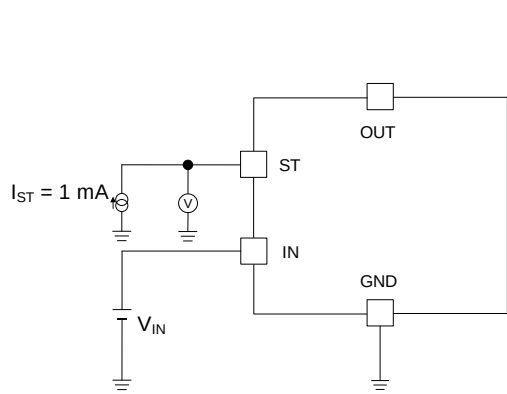


Measurement Circuit for Figure 24, 25

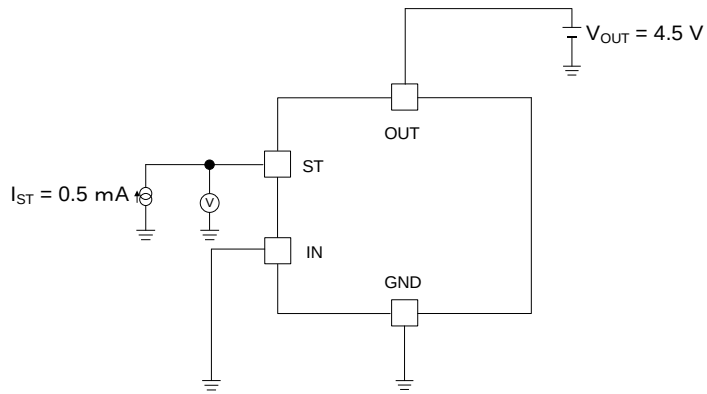


Measurement Circuit for Figure 26

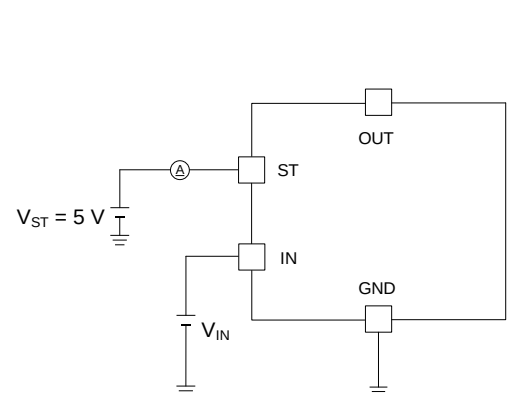
Measurement Circuit for Typical Performance Curves – continued



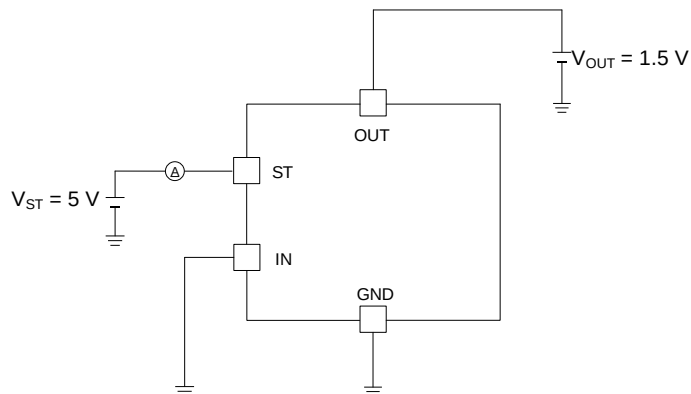
Measurement Circuit for Figure 27



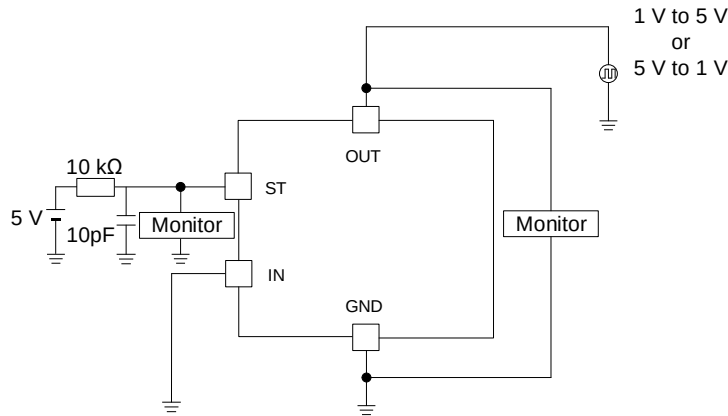
Measurement Circuit for Figure 28



Measurement Circuit for Figure 29



Measurement Circuit for Figure 30



Measurement Circuit for Figure 31, 32

I/O Pin Truth Table

■ Output Function

Input Signal	Operating Status	Output Status
L	Standby	OFF
H	Normal	ON
H	Over Current	Current Limiting
H	Over Temperature	OFF

■ Diagnostic Function of Abnormal Status

Diagnoses the presence or absence of an abnormal condition. By combining High and Low of the input signal and the ST pin, it is possible to grasp overcurrent, heating state, load open state.

Input Signal	ST Signal	Diagnosis Result
L	L	No Abnormality
L	H	Load Open
H	L	Over Current or Over Temperature
H	H	No Abnormality

Timing Chart

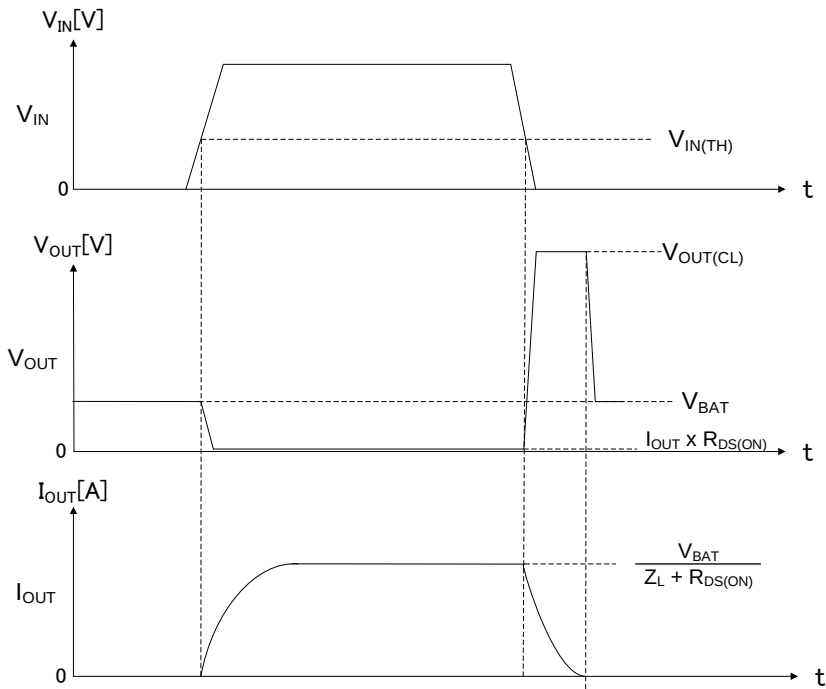


Figure 34. Inductive Load Operation

Timing Chart – continued

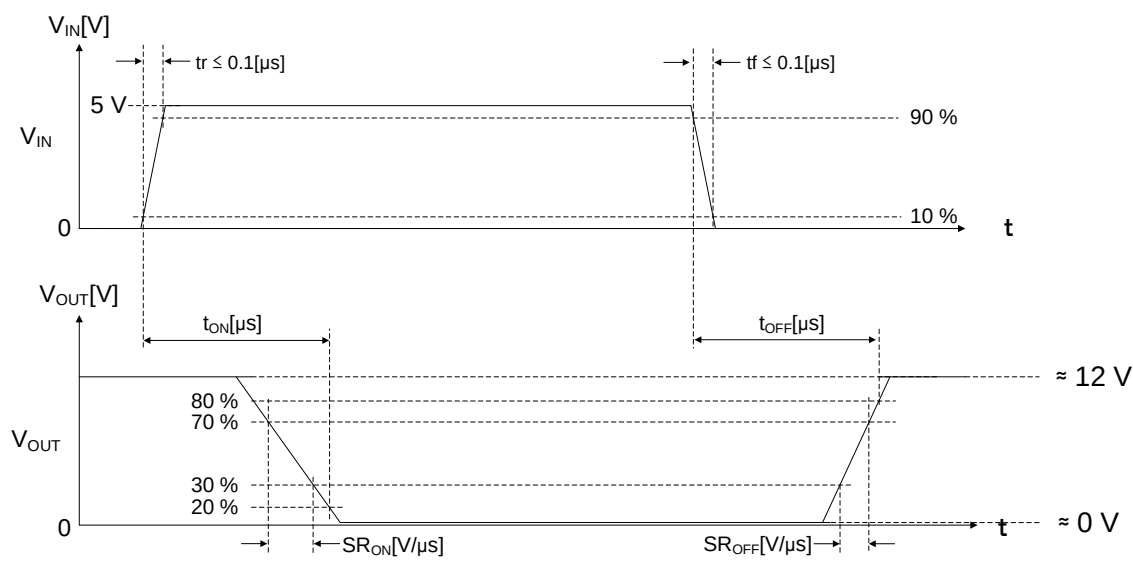


Figure 35. Switching Time

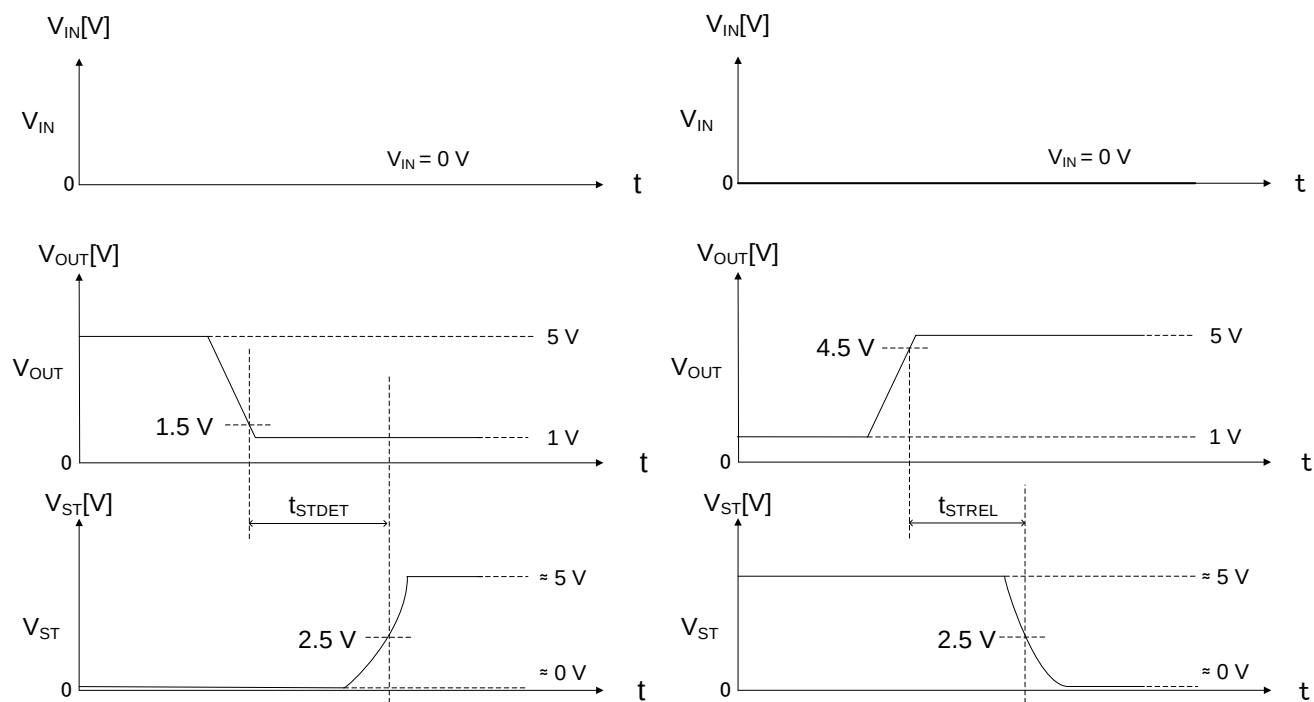


Figure 36. ST Output Delay Time

Function Description

■ Over Current Protection Function

This IC has OCP function. Following is shown that the timing chart of OCP function.

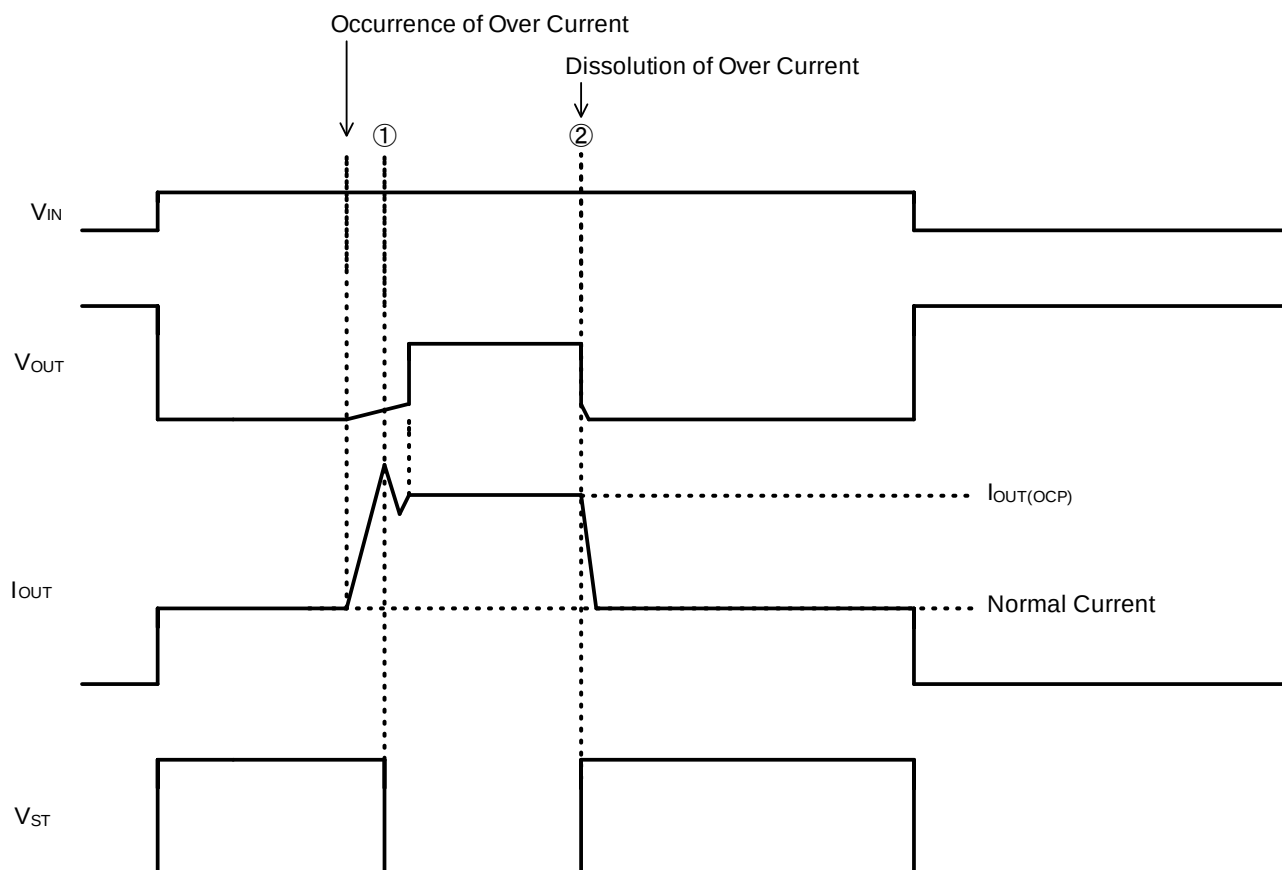


Figure 37. Timing Chart of OCP Function

- ① I_{OUT} is limited at Over Current Limitation Level ($I_{OUT(OCF)} = 6\text{ A (Typ)}$) and the V_{OUT} rises when over current is occurred. V_{ST} turns Low.
- ② Current limitation is released when over current is occurred. V_{ST} turns High.

Function Description – continued

■ TSD Function

This IC has a built-in TSD function. Following is shown that the timing chart of TSD function.

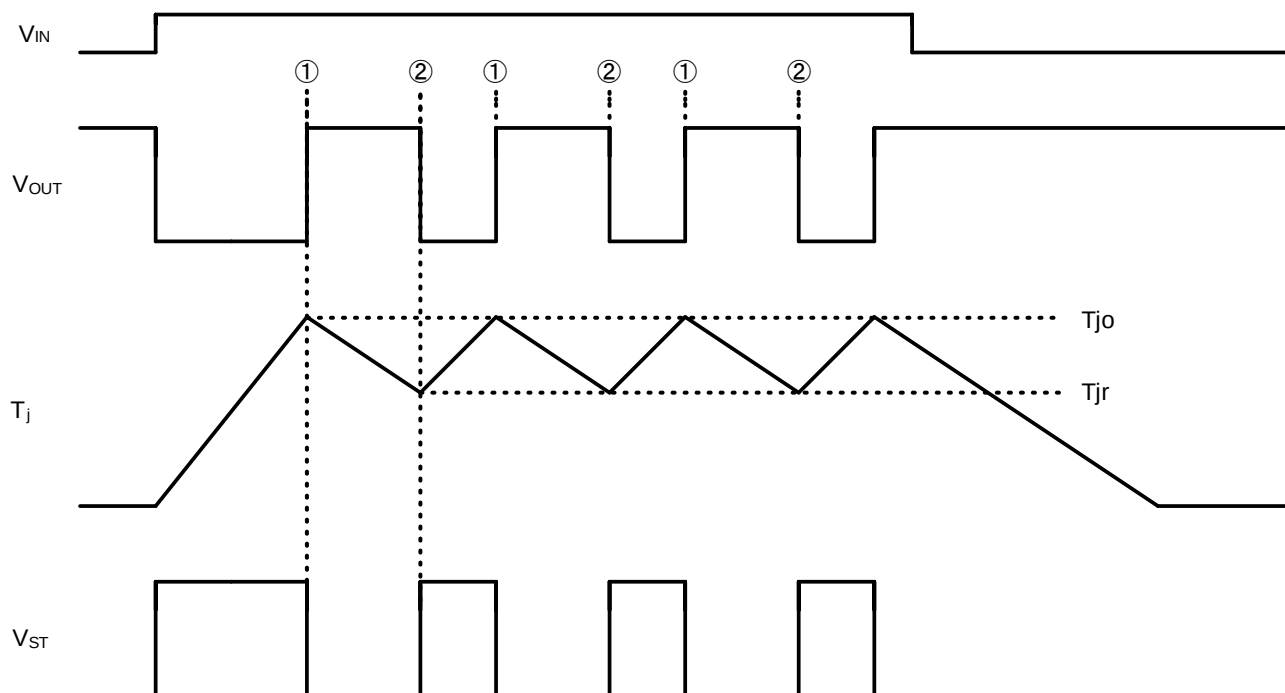


Figure 38. Timing Chart of TSD Function

- ① The output is turned off when the temperature of the IC reaches Thermal Shutdown Detected Temperature (T_{jo}) = 175 °C (Typ) or more. V_{ST} turns Low.
- ② The output returns to its normal state when the temperature of the IC becomes Thermal Shutdown Released Temperature (T_{jr}) = 135 °C (Min) or less. V_{ST} turns High.

Operational Notes

1. Ground Voltage

Ensure that no pins are at a voltage below that of the ground pin at any time, even during transient condition.

2. Ground Wiring Pattern

When using both small-signal and large-current ground traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the ground traces of external components do not cause variations on the ground voltage. The ground lines must be as short and thick as possible to reduce line impedance.

3. Recommended Operating Conditions

The function and operation of the IC are guaranteed within the range specified by the recommended operating conditions. The characteristic values are guaranteed only under the conditions of each item specified by the electrical characteristics.

4. Testing on Application Boards

When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.

5. Inter-pin Short and Mounting Errors

Ensure that the direction and position are correct when mounting the IC on the PCB. Incorrect mounting may result in damaging the IC. Avoid nearby pins being shorted to each other especially to ground, power supply and output pin. Inter-pin shorts could be due to many reasons such as metal particles, water droplets (in very humid environment) and unintentional solder bridge deposited in between pins during assembly to name a few.

6. Ceramic Capacitor

When using a ceramic capacitor, determine a capacitance value considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

7. Thermal Shutdown Function (TSD)

This IC has a built-in thermal shutdown function that prevents heat damage to the IC. Normal operation should always be within the IC's maximum junction temperature rating. If however the rating is exceeded for a continued period, the junction temperature (T_j) will rise which will activate the TSD function that will turn OFF power output pins. When the T_j falls below the TSD threshold, the circuits are automatically restored to normal operation.

Note that the TSD function operates in a situation that exceeds the absolute maximum ratings and therefore, under no circumstances, should the TSD function be used in a set design or for any purpose other than protecting the IC from heat damage.

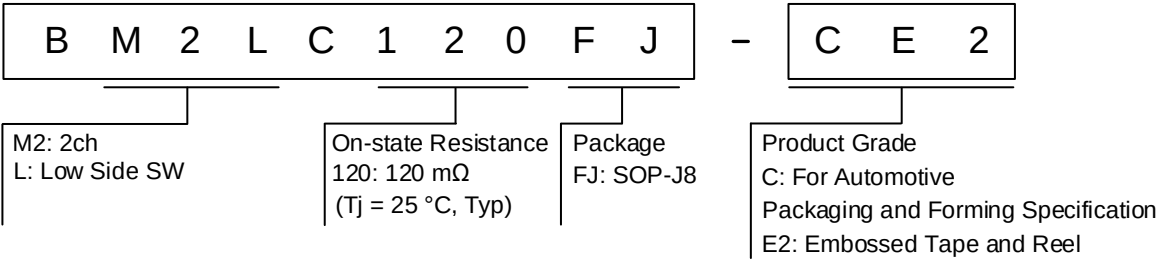
8. Over Current Protection Function (OCP)

This IC incorporates an integrated over current protection function that is activated when the load is shorted. This protection function is effective in preventing damage due to sudden and unexpected incidents. However, the IC should not be used in applications characterized by continuous operation or transitioning of the protection function.

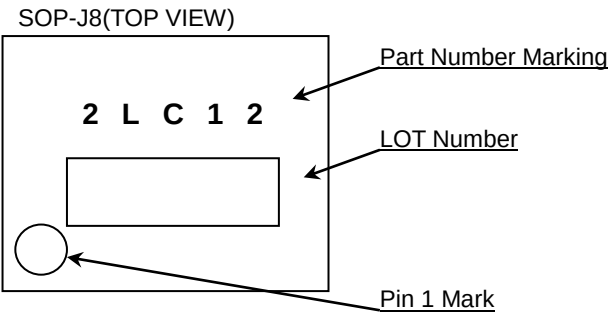
9. Active Clamp Operation

The IC integrates the active clamp function to internally absorb the reverse energy which is generated when the inductive load is turned off. When the active clamp operates, the thermal shutdown function does not work. Please do not exceed active clamp endurance when inductive load is used.

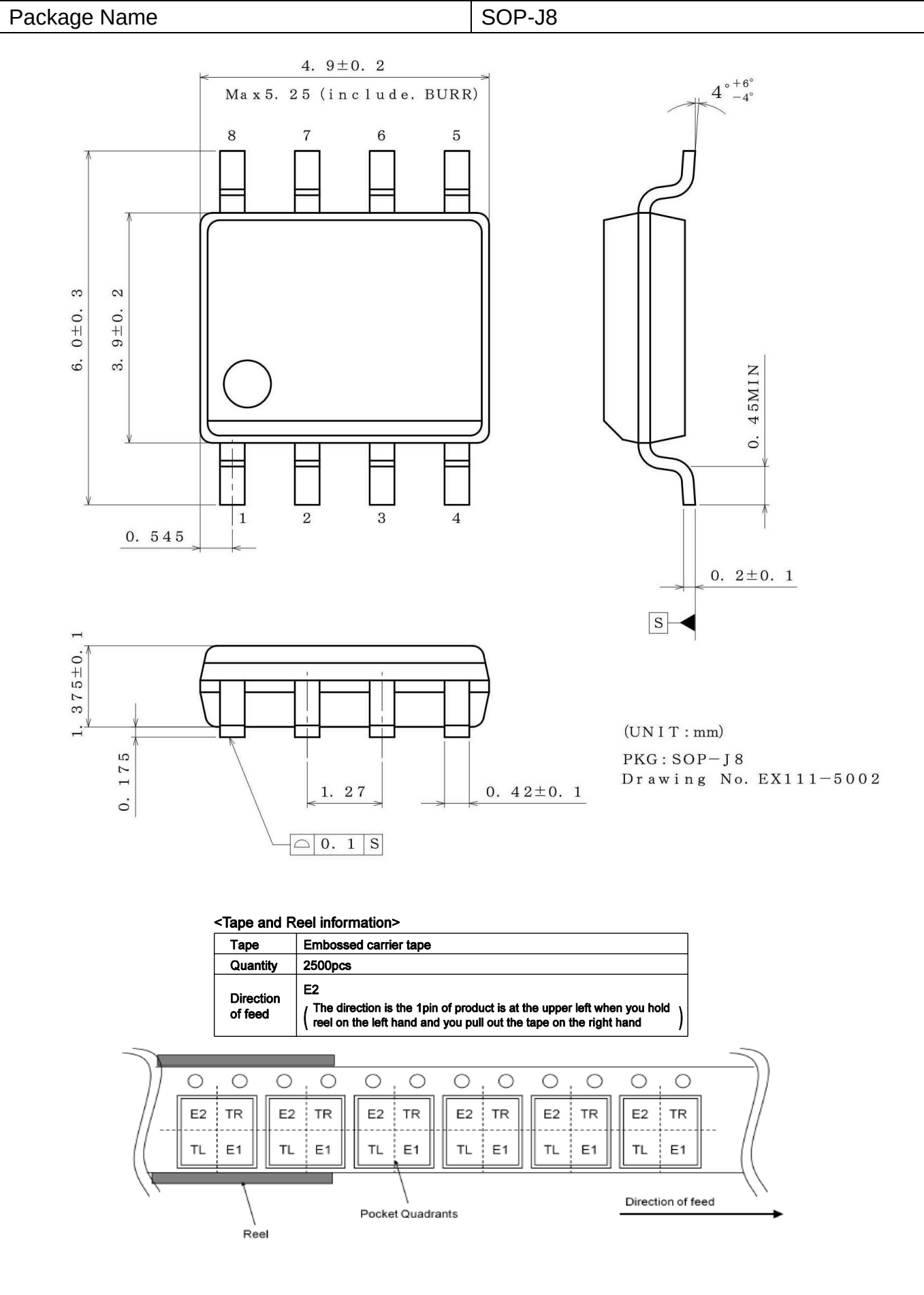
Ordering Information



Marking Diagram



Physical Dimension and Packing Information



Revision History

Date	Revision	Changes
26.Feb.2018	001	New Release
09.Apr.2018	002	P4 Absolute Maximum Ratings Diagnostic output voltage and Diagnostic output current were added.
25.Jul.2018	003	P9 Electrical Characteristics Slew Rate On and S Slew Rate Off limits were corrected. P13 Figjre 17, 18, 19 and 20 were corrected.
25.May.2020	004	P22, P23 Function Description Descriptions of Over Current Protection Function and TSD

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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